



PCNNumber: 1315
Chgnot.doc rev 10 04/13 - NO

Product/Process Change Notification (PCN)

Customer: North American & Asia Distributors

Date: 10/11/2013

Customer Part # and/Allegro part #:

A8304SESTR-T

Originator: J. Hurley

Phone: 508-854-5491 **Fax:** 508-853-3353

Duration of Change:

Permanent Temporary (explain)

Summary description of change: Part Change: Process Change: Other:

Allegro currently assembles the 3 x 3 QFN package type at Stats ChipPAC, Kuala Lumpur, Malaysia, (SCM). Stats ChipPAC Malaysia (SCM) has informed Allegro that they will be closing this facility in June of 2014. Allegro will move the assembly site for the 3 x 3 QFN package type from Stats ChipPAC Malaysia (SCM) to Carsem Suzhou, China (CRC).

What is the part or process changing from (provide details)?

Allegro currently assembles the 3 x 3 QFN package type at Stats ChipPAC, Kuala Lumpur, Malaysia. Stats ChipPAC Malaysia (SCM) has informed Allegro that they will be closing this facility in June of 2014.

What is the part or process changing to (provide details)?

Allegro will move the assembly site for the 3 x 3 QFN package type to Carsem Suzhou, China.

Describe how this change affects the customer:

Carsem Suzhou, China has been primary QFN source for many years. Allegro has performed the necessary qualification and electrical tests to ensure the device is functionally equivalent to the data sheet specification.



Expected completion date for internal qualification: Complete

Expected PPAP availability date: N/A

Target implementation date: December 2013

Estimated date of first shipment: January 2014

Expected sample availability date: December 2013

Customer Approval Required: For Notification Only

No

cc: Allegro Sales/Marketing/Quality